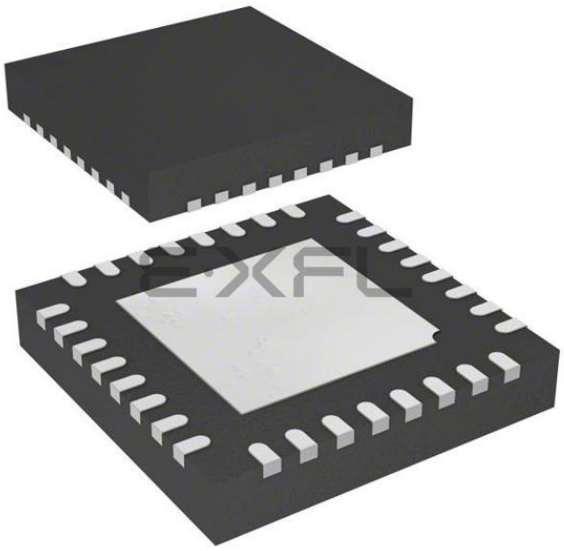

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	27
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 10x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-UFQFN Exposed Pad
Supplier Device Package	32-UFQFPN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/stm32l031k6u6tr

3.14.4 Independent watchdog (IWDG)

The independent watchdog is based on a 12-bit downcounter and 8-bit prescaler. It is clocked from an independent 37 kHz internal RC and, as it operates independently of the main clock, it can operate in Stop and Standby modes. It can be used either as a watchdog to reset the device when a problem occurs, or as a free-running timer for application timeout management. It is hardware- or software-configurable through the option bytes. The counter can be frozen in debug mode.

3.14.5 Window watchdog (WWDG)

The window watchdog is based on a 7-bit downcounter that can be set as free-running. It can be used as a watchdog to reset the device when a problem occurs. It is clocked from the main clock. It has an early warning interrupt capability and the counter can be frozen in debug mode.

3.15 Communication interfaces

3.15.1 I^2C bus

One I^2C interface (I2C1) can operate in multimaster or slave modes. The I^2C interface can support Standard mode (Sm, up to 100 kbit/s), Fast mode (Fm, up to 400 kbit/s) and Fast Mode Plus (Fm+, up to 1 Mbit/s) with 20 mA output drive on some I/Os.

The I^2C interface supports 7-bit and 10-bit addressing modes, multiple 7-bit slave addresses (2 addresses, 1 with configurable mask). They also include programmable analog and digital noise filters.

Table 10. Comparison of I2C analog and digital filters

	Analog filter	Digital filter
Pulse width of suppressed spikes	≥ 50 ns	Programmable length from 1 to 15 I2C peripheral clocks
Benefits	Available in Stop mode	1. Extra filtering capability vs. standard requirements. 2. Stable length
Drawbacks	Variations depending on temperature, voltage, process	Wakeup from Stop on address match is not available when digital filter is enabled.

In addition, I2C1 provides hardware support for SMBus 2.0 and PMBus 1.1: ARP capability, Host notify protocol, hardware CRC (PEC) generation/verification, timeouts verifications and ALERT protocol management. I2C1 also has a clock domain independent from the CPU clock, allowing the I2C1 to wake up the MCU from Stop mode on address match.

The I2C interface can be served by the DMA controller.

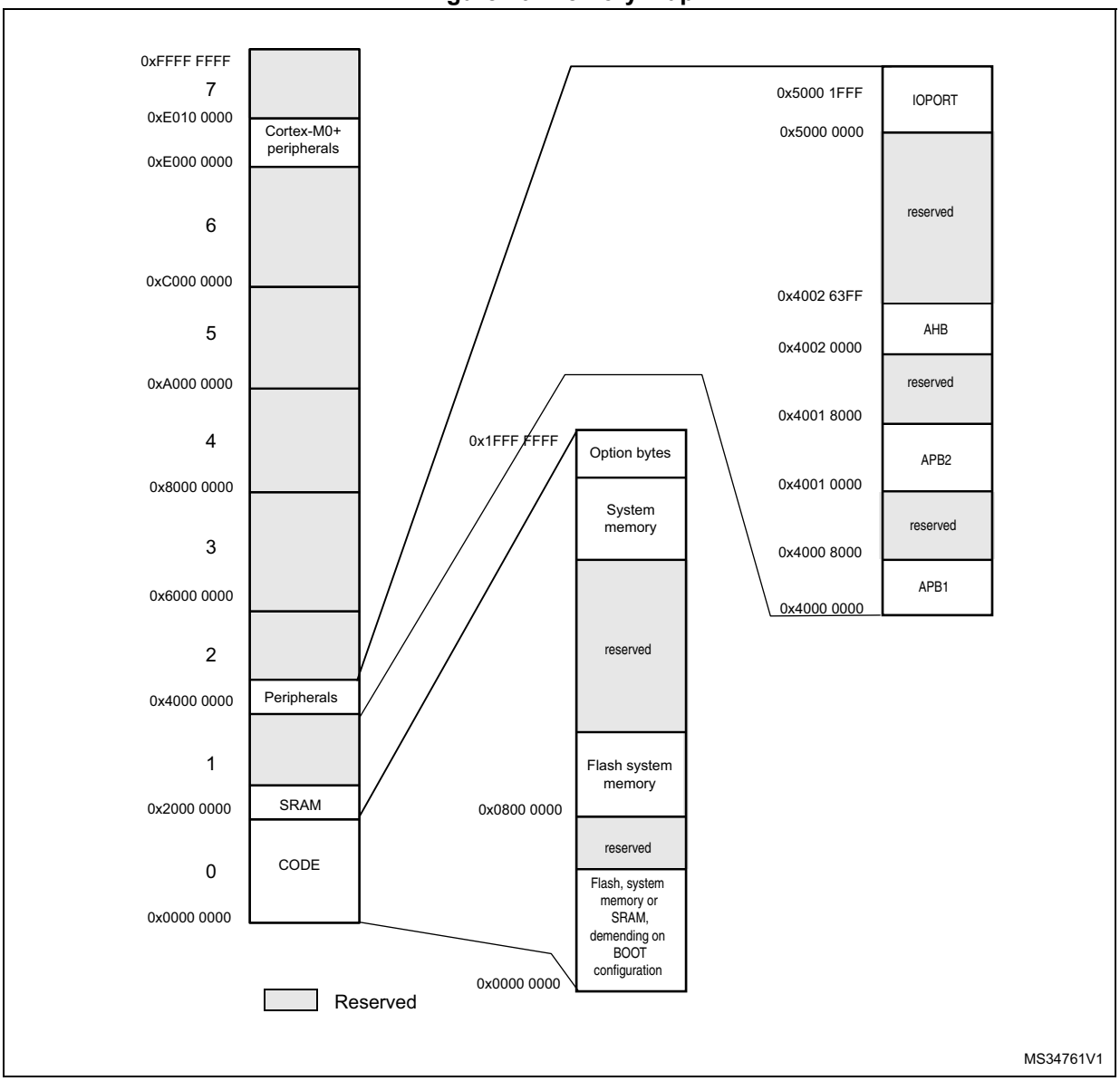
Refer to *Table 11* for the supported modes and features of I2C interface.

Table 15. Pin definitions (continued)

Pin Number							Pin name (function after reset)	Pin type	I/O structure	Note	Alternate functions	Additional functions
TSSOP20	WLCSP25[1]	UFQFPN28	UFQFPN28 (STM32L031GxUxS only)	LQFP32	UFQFPN32[2]	LQFP48						
-	-	-	-	-	-	35	VSS	S	-	-	-	-
-	D1	-	-	-	-	36	VDD	S	-	-	-	-
20	A2	22	22	24	24	37	PA14	I/O	FT	-	SWCLK, LPTIM1_OUT, I2C1_SMBA, USART2_TX, LPUART1_TX	-
-	-	23	23	25	25	38	PA15	I/O	FT	-	SPI1_NSS, TIM2_ETR, EVENTOUT, USART2_RX, TIM2_CH1	--
-	B2	24	24	26	26	39	PB3	I/O	FT	-	SPI1_SCK, TIM2_CH2, EVENTOUT	COMP2_INN
-	-	-	25	27	27	40	PB4	I/O	FT	-	SPI1_MISO, EVENTOUT, TIM22_CH1	COMP2_INP
-	-	-	26	28	28	41	PB5	I/O	FT	-	SPI1_MOSI, LPTIM1_IN1, I2C1_SMBA, TIM22_CH2	COMP2_INP
-	A3	25	27	29	29	42	PB6	I/O	FTf	-	USART2_TX, I2C1_SCL, LPTIM1_ETR, TIM21_CH1	COMP2_INP
-	A4	26	28	30	30	43	PB7	I/O	FTf	-	USART2_RX, I2C1_SDA, LPTIM1_IN2	COMP2_INP, VREF_PVD_IN

5 Memory mapping

Figure 10. Memory map



1. Refer to the STM32L031x4/6 reference manual for details on the Flash memory organization for each memory size.

6 Electrical characteristics

6.1 Parameter conditions

Unless otherwise specified, all voltages are referenced to V_{SS}.

6.1.1 Minimum and maximum values

Unless otherwise specified the minimum and maximum values are guaranteed in the worst conditions of ambient temperature, supply voltage and frequencies by tests in production on 100% of the devices with an ambient temperature at T_A = 25 °C and T_A = $T_A$max (given by the selected temperature range).

Data based on characterization results, design simulation and/or technology characteristics are indicated in the table footnotes and are not tested in production. Based on characterization, the minimum and maximum values refer to sample tests and represent the mean value plus or minus three times the standard deviation (mean±3σ).

6.1.2 Typical values

Unless otherwise specified, typical data are based on T_A = 25 °C, V_{DD} = 3.6 V (for the 1.65 V ≤ V_{DD} ≤ 3.6 V voltage range). They are given only as design guidelines and are not tested.

Typical ADC accuracy values are determined by characterization of a batch of samples from a standard diffusion lot over the full temperature range, where 95% of the devices have an error less than or equal to the value indicated (mean±2σ).

6.1.3 Typical curves

Unless otherwise specified, all typical curves are given only as design guidelines and are not tested.

6.1.4 Loading capacitor

The loading conditions used for pin parameter measurement are shown in *Figure 11*.

6.1.5 Pin input voltage

The input voltage measurement on a pin of the device is described in *Figure 12*.

Figure 11. Pin loading conditions

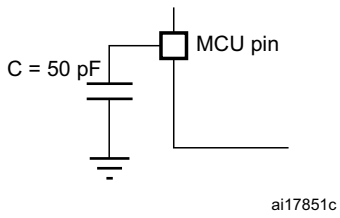


Figure 12. Pin input voltage

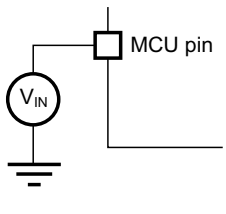


Table 28. Current consumption in Sleep mode

Symbol	Parameter	Conditions		f_{HCLK}	Typ	Max(1)	Unit
I_{DD} (Sleep)	Supply current in Sleep mode, Flash memory OFF	f_{HSE} = f_{HCLK} up to 16 MHz included, f_{HSE} = f_{HCLK}/2 above 16 MHz (PLL ON)(2)	Range 3, V_{CORE}=1.2 V, VOS[1:0]=11	1 MHz	36.5	87	µA
				2 MHz	58	100	
				4 MHz	100	170	
			Range 2, V_{CORE}=1.5 V, VOS[1:0]=10	4 MHz	125	190	
				8 MHz	230	310	
				16 MHz	450	540	
			Range 1, V_{CORE}=1.8 V, VOS[1:0]=01	8 MHz	275	360	
				16 MHz	555	650	
				32 MHz	1350	1600	
		HSI16 clock source (16 MHz)	Range 2, V_{CORE}=1.5 V, VOS[1:0]=10	16 MHz	585	690	
			Range 1, V_{CORE}=1.8 V, VOS[1:0]=01	32 MHz	1500	1700	
		MSI clock	Range 3, V_{CORE}=1.2 V, VOS[1:0]=11	65 kHz	17	43	
				524 kHz	28	55	
				4.2 MHz	115	190	
	Supply current in Sleep mode, Flash memory ON	f_{HSE} = f_{HCLK} up to 16 MHz included, f_{HSE} = f_{HCLK}/2 above 16 MHz (PLL ON)(2)	Range 3, V_{CORE}=1.2 V, VOS[1:0]=11	1 MHz	49	160	
				2 MHz	69	190	
				4 MHz	115	230	
			Range 2, $_{CORE}$=1.5 V, VOS[1:0]=10	4 MHz	135	200	
				8 MHz	240	320	
				16 MHz	460	550	
			Range 1, V_{CORE}=1.8 V, VOS[1:0]=01	8 MHz	290	370	
				16 MHz	565	670	
				32 MHz	1350	1600	
		HSI16 clock source (16 MHz)	Range 2, V_{CORE}=1.5 V, VOS[1:0]=10	16 MHz	600	700	
			Range 1, V_{CORE}=1.8 V, VOS[1:0]=01	32 MHz	1500	1700	
		MSI clock	Range 3, V_{CORE}=1.2 V, VOS[1:0]=11	65 kHz	28	55	
				524 kHz	39.5	67	
				4.2 MHz	125	200	

1. Guaranteed by characterization results at 125 °C, unless otherwise specified.
2. Oscillator bypassed (HSEBYP = 1 in RCC_CR register).

Table 31. Typical and maximum current consumptions in Stop mode

Symbol	Parameter	Conditions	Typ	Max(1)	Unit
I_{DD} (Stop)	Supply current in Stop mode	T_A = -40°C to 25°C	0.38	0.99	µA
		T_A = 55°C	0.54	1.9	
		T_A= 85°C	1.35	4.2	
		T_A = 105°C	3.1	9	
		T_A = 125°C	7.55	19	

1. Guaranteed by characterization results at 125 °C, unless otherwise specified.

Figure 18. I_{DD} vs V_{DD}, at T_A= 25/55/ 85/105/125 °C, Stop mode with RTC enabled and running on LSE Low drive

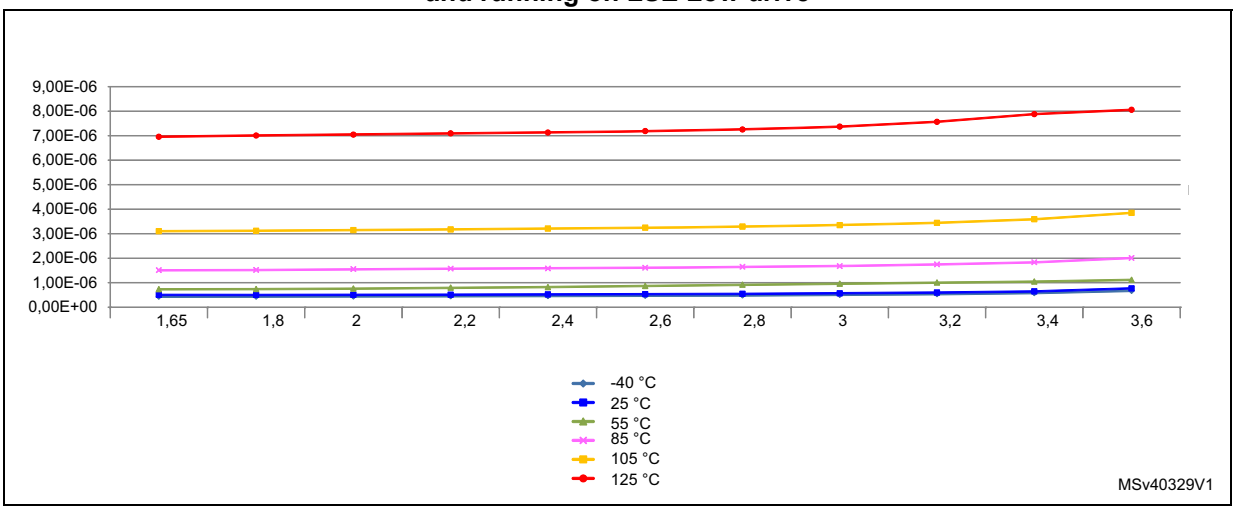


Figure 19. I_{DD} vs V_{DD}, at T_A= 25/55/85/105/125 °C, Stop mode with RTC disabled, all clocks off

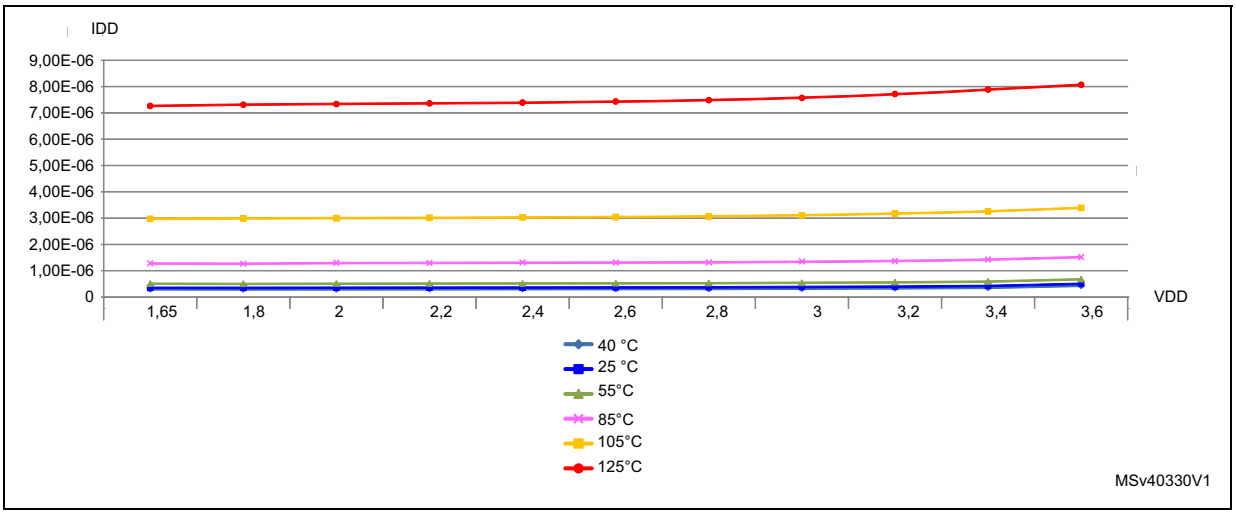


Table 35. Peripheral current consumption in Stop and Standby mode(1)

Symbol	Peripheral	Typical consumption, T_A = 25 °C		Unit
		V_{DD}=1.8 V	V_{DD}=3.0 V	
$I_{DD(PVD / BOR)}$	-	0.7	1.2	µA
I_{REFINT}	-	1.3	1.4	
-	LSE Low drive(2)	0.1	0.1	
-	LSI	0.27	0.31	
-	IWDG	0.2	0.3	
-	LPTIM1, Input 100 Hz	0.01	0.01	
-	LPTIM1, Input 1 MHz	6	6	
-	LPUART1	0.2	0.2	
-	RTC (LSE in Bypass mode)	0.2	0.2	

1. LPTIM, LPUART peripherals can operate in Stop mode but not in Standby mode
2. LSE Low drive consumption is the difference between an external clock on OSC32_IN and a quartz between OSC32_IN and OSC32_OUT.-

6.3.5 Wakeup time from low-power mode

The wakeup times given in the following table are measured with the MSI or HSI16 RC oscillator. The clock source used to wake up the device depends on the current operating mode:

- Sleep mode: the clock source is the clock that was set before entering Sleep mode
- Stop mode: the clock source is either the MSI oscillator in the range configured before entering Stop mode, the HSI16 or HSI16/4.
- Standby mode: the clock source is the MSI oscillator running at 2.1 MHz

All timings are derived from tests performed under ambient temperature and V_{DD} supply voltage conditions summarized in *Table 20*.

Table 43. MSI oscillator characteristics (continued)

Symbol	Parameter	Condition	Typ	Max	Unit
$t_{SU(MSI)}$	MSI oscillator startup time	MSI range 0	30	-	µs
		MSI range 1	20	-	
		MSI range 2	15	-	
		MSI range 3	10	-	
		MSI range 4	6	-	
		MSI range 5	5	-	
		MSI range 6, Voltage range 1 and 2	3.5	-	
		MSI range 6, Voltage range 3	5	-	
$t_{STAB(MSI)}$(2)	MSI oscillator stabilization time	MSI range 0	-	40	µs
		MSI range 1	-	20	
		MSI range 2	-	10	
		MSI range 3	-	4	
		MSI range 4	-	2.5	
		MSI range 5	-	2	
		MSI range 6, Voltage range 1 and 2	-	2	
		MSI range 3, Voltage range 3	-	3	
$f_{OVER(MSI)}$	MSI oscillator frequency overshoot	Any range to range 5	-	4	MHz
		Any range to range 6	-	6	

1. This is a deviation for an individual part, once the initial frequency has been measured.
2. Guaranteed by characterization results.

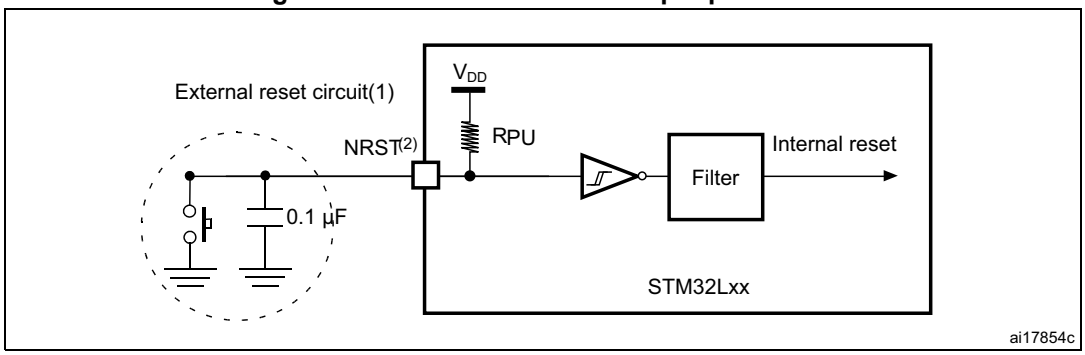
6.3.8 PLL characteristics

The parameters given in *Table 44* are derived from tests performed under ambient temperature and V_{DD} supply voltage conditions summarized in *Table 20*.

Table 44. PLL characteristics

Symbol	Parameter	Value			Unit
		Min	Typ	Max(1)	
f_{PLL_IN}	PLL input clock(2)	2	-	24	MHz
	PLL input clock duty cycle	45	-	55	%

Figure 28. Recommended NRST pin protection



1. The reset network protects the device against parasitic resets.
2. The user must ensure that the level on the NRST pin can go below the $V_{IL(NRST)}$ max level specified in *Table 56*. Otherwise the reset will not be taken into account by the device.

6.3.15 12-bit ADC characteristics

Unless otherwise specified, the parameters given in *Table 57* are values derived from tests performed under ambient temperature, f_{PCLK} frequency and V_{DDA} supply voltage conditions summarized in *Table 20: General operating conditions*.

Note: It is recommended to perform a calibration after each power-up.

Table 57. ADC characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DDA}	Analog supply voltage for ADC on	Fast channel	1.65	-	3.6	V
		Standard channel	1.75(1)	-	3.6	
$I_{DDA\ (ADC)}$	Current consumption of the ADC on V_{DDA}	1.14 Msps	-	200	-	µA
		10 ksps	-	40	-	
	Current consumption of the ADC on V_{DD}(2)	1.14 Msps	-	70	-	
		10 ksps	-	1	-	
f_{ADC}	ADC clock frequency	Voltage scaling Range 1	0.14	-	16	MHz
		Voltage scaling Range 2	0.14	-	8	
		Voltage scaling Range 3	0.14	-	4	
f_S(3)	Sampling rate		0.05	-	1.14	MHz
f_{TRIG}(3)	External trigger frequency	f_{ADC} = 16 MHz	-	-	941	kHz
			-	-	17	$1/f_{ADC}$
V_{AIN}	Conversion voltage range		0	-	V_{DDA}	V
R_{AIN}(3)	External input impedance	See *Equation 1* and *Table 58* for details	-	-	50	kΩ
R_{ADC}(3)(4)	Sampling switch resistance		-	-	1	kΩ
C_{ADC}(3)	Internal sample and hold capacitor		-	-	8	pF

Table 58. R_{AIN} max for f_{ADC} = 16 MHz(1)

T_s (cycles)	t_S (µs)	R_{AIN} max for fast channels (kΩ)	R_{AIN} max for standard channels (kΩ)						
			V_{DD} > 2.7 V	V_{DD} > 2.4 V	V_{DD} > 2.0 V	V_{DD} > 1.8 V	V_{DD} > 1.75 V	V_{DD} > 1.65 V and T_A > –10 °C	V_{DD} > 1.65 V and T_A > 25 °C
1.5	0.09	0.5	< 0.1	NA	NA	NA	NA	NA	NA
3.5	0.22	1	0.2	< 0.1	NA	NA	NA	NA	NA
7.5	0.47	2.5	1.7	1.5	< 0.1	NA	NA	NA	NA
12.5	0.78	4	3.2	3	1	NA	NA	NA	NA
19.5	1.22	6.5	5.7	5.5	3.5	NA	NA	NA	< 0.1
39.5	2.47	13	12.2	12	10	NA	NA	NA	5
79.5	4.97	27	26.2	26	24	< 0.1	NA	NA	19
160.5	10.03	50	49.2	49	47	32	< 0.1	< 0.1	42

1. Guaranteed by design.

Table 59. ADC accuracy(1)(2)(3)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
ET	Total unadjusted error	1.65 V < V_{DDA} < 3.6 V, range 1/2/3	-	2	4	LSB
EO	Offset error		-	1	2.5	
EG	Gain error		-	1	2	
EL	Integral linearity error		-	1.5	2.5	
ED	Differential linearity error		-	1	1.5	
ENOB	Effective number of bits		10.2	11		bits
	Effective number of bits (16-bit mode oversampling with ratio =256)(4)		11.3	12.1	-	
SINAD	Signal-to-noise distortion		63	69	-	dB
SNR	Signal-to-noise ratio		63	69	-	
	Signal-to-noise ratio (16-bit mode oversampling with ratio =256)(4)		70	76	-	
THD	Total harmonic distortion		-	-85	-73	

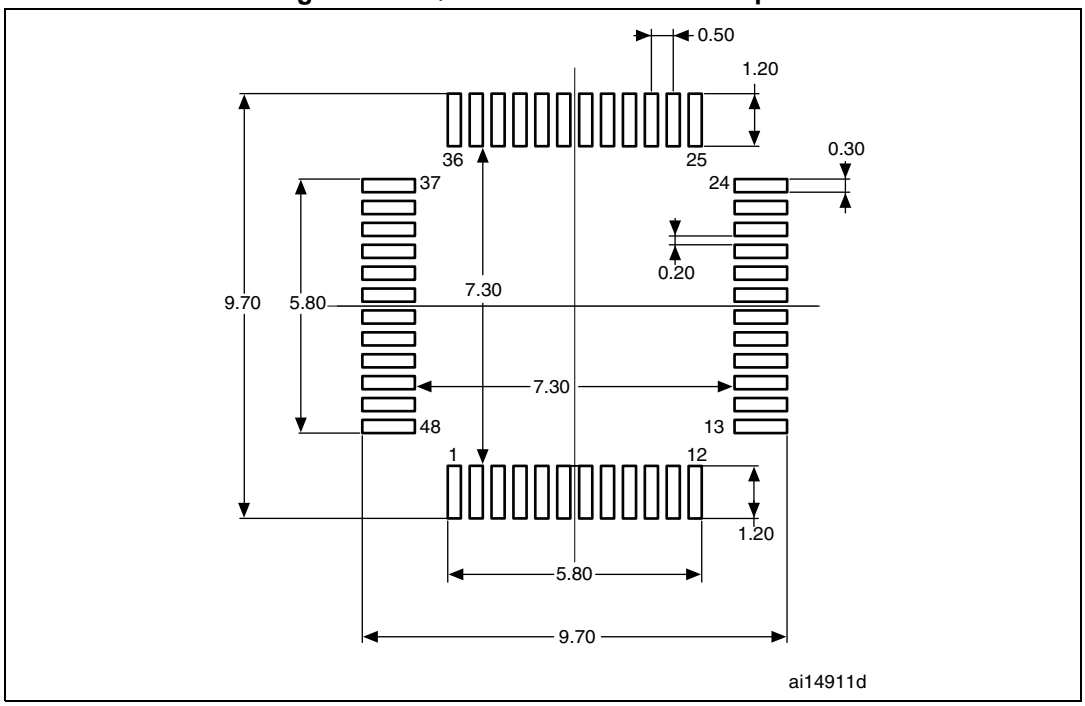
1. ADC DC accuracy values are measured after internal calibration.
2. ADC Accuracy vs. Negative Injection Current: Injecting negative current on any of the standard (non-robust) analog input pins should be avoided as this significantly reduces the accuracy of the conversion being performed on another analog input. It is recommended to add a Schottky diode (pin to ground) to standard analog pins which may potentially inject negative current.
   Any positive injection current within the limits specified for $I_{INJ(PIN)}$ and $\Sigma I_{INJ(PIN)}$ in *Section 6.3.12* does not affect the ADC accuracy.
3. Better performance may be achieved in restricted V_{DDA}, frequency and temperature ranges.
4. This number is obtained by the test board without additional noise, resulting in non-optimized value for oversampling mode.

Table 68. SPI characteristics in voltage Range 2 (1)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{SCK} $1/t_{c(SCK)}$	SPI clock frequency	Master mode	-	-	8	MHz
		Slave mode Transmitter $1.65<V_{DD}<3.6V$			8	
		Slave mode Transmitter $2.7<V_{DD}<3.6V$			8(2)	
$Duty_{(SCK)}$	Duty cycle of SPI clock frequency	Slave mode	30	50	70	%
$t_{su(NSS)}$	NSS setup time	Slave mode, SPI presc = 2	4*Tpclk	-	-	ns
$t_{h(NSS)}$	NSS hold time	Slave mode, SPI presc = 2	2*Tpclk	-	-	
$t_{w(SCKH)}$ $t_{w(SCKL)}$	SCK high and low time	Master mode	Tpclk-2	Tpclk	Tpclk+2	
$t_{su(MI)}$	Data input setup time	Master mode	12	-	-	
$t_{su(SI)}$		Slave mode	11	-	-	
$t_{h(MI)}$	Data input hold time	Master mode	6.5	-	-	
$t_{h(SI)}$		Slave mode	2	-	-	
$t_{a(SO}$	Data output access time	Slave mode	18	-	52	
$t_{dis(SO)}$	Data output disable time	Slave mode	12	-	42	
$t_{v(SO)}$	Data output valid time	Slave mode	-	40	55	
		Master mode	-	16	26	
$t_{v(MO)}$	Data output hold time	Slave mode	12	-	-	
$t_{h(SO)}$		Master mode	4	-	-	

1. Guaranteed by characterization results.
2. The maximum SPI clock frequency in slave transmitter mode is determined by the sum of $t_{v(SO)}$ and $t_{su(MI)}$ which has to fit into SCK low or high phase preceding the SCK sampling edge. This value can be achieved when the SPI communicates with a master having $t_{su(MI)}$ = 0 while $Duty_{(SCK)}$ = 50%.

Figure 35. LQFP48 recommended footprint

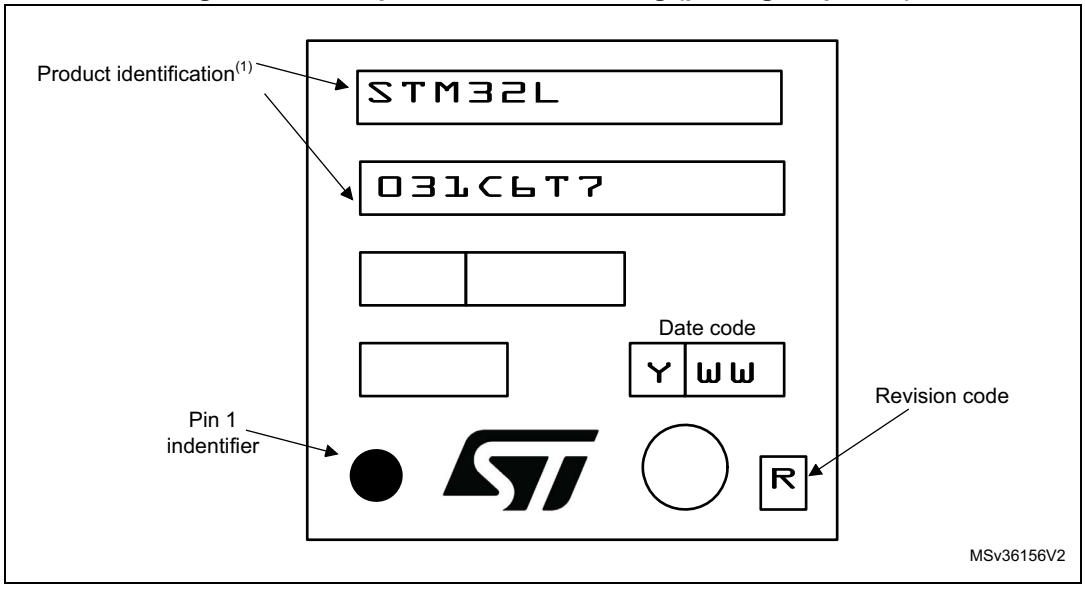


1. Dimensions are expressed in millimeters.

LQFP48 device marking

The following figure gives an example of topside marking versus pin 1 position identifier location.

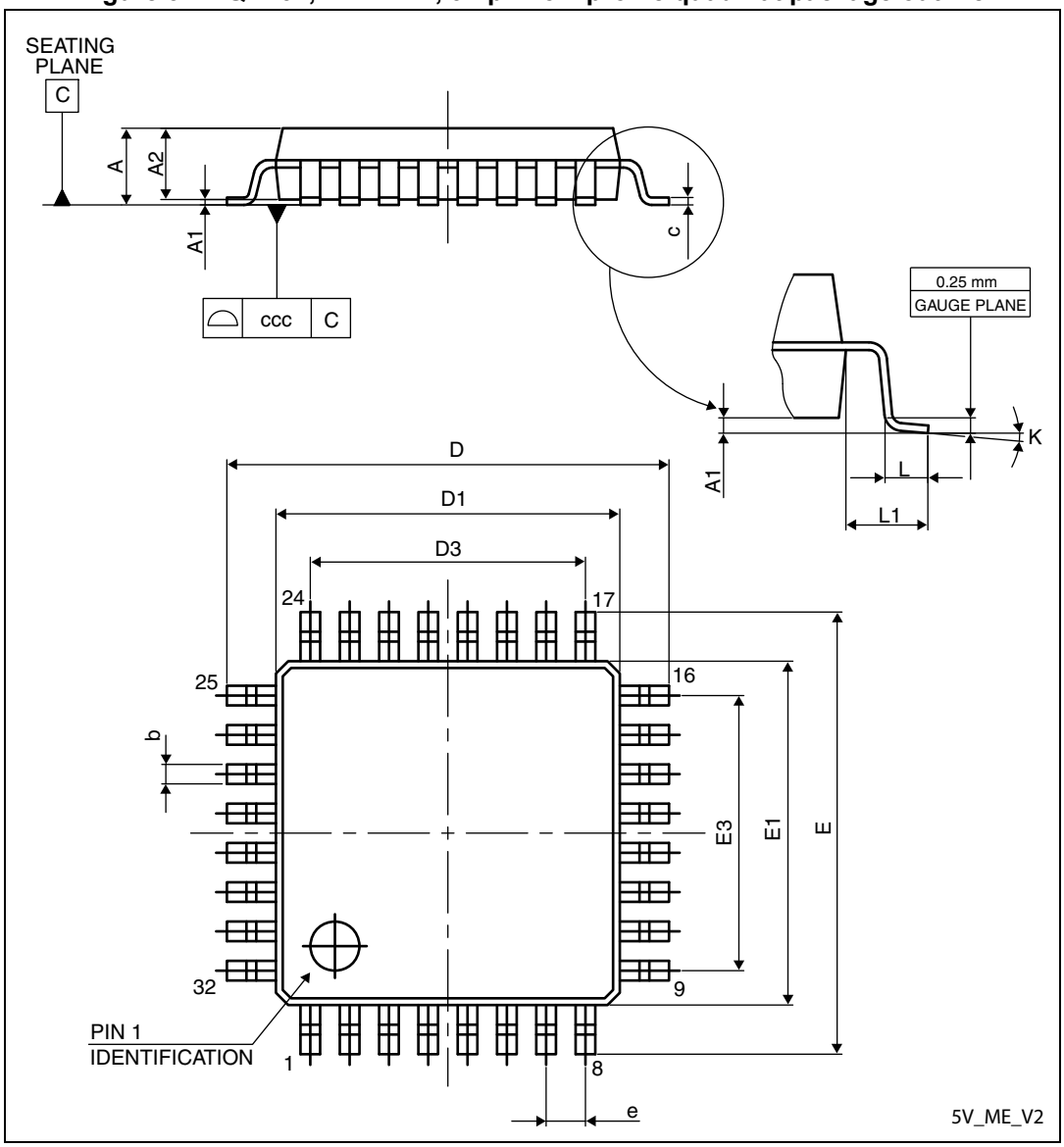
Figure 36. Example of LQFP48 marking (package top view)



1. Parts marked as “ES”, “E” or accompanied by an Engineering Sample notification letter, are not yet qualified and therefore not yet ready to be used in production and any consequences deriving from such usage will not be at ST charge. In no event, ST will be liable for any customer usage of these engineering samples in production. ST Quality has to be contacted prior to any decision to use these Engineering samples to run qualification activity.

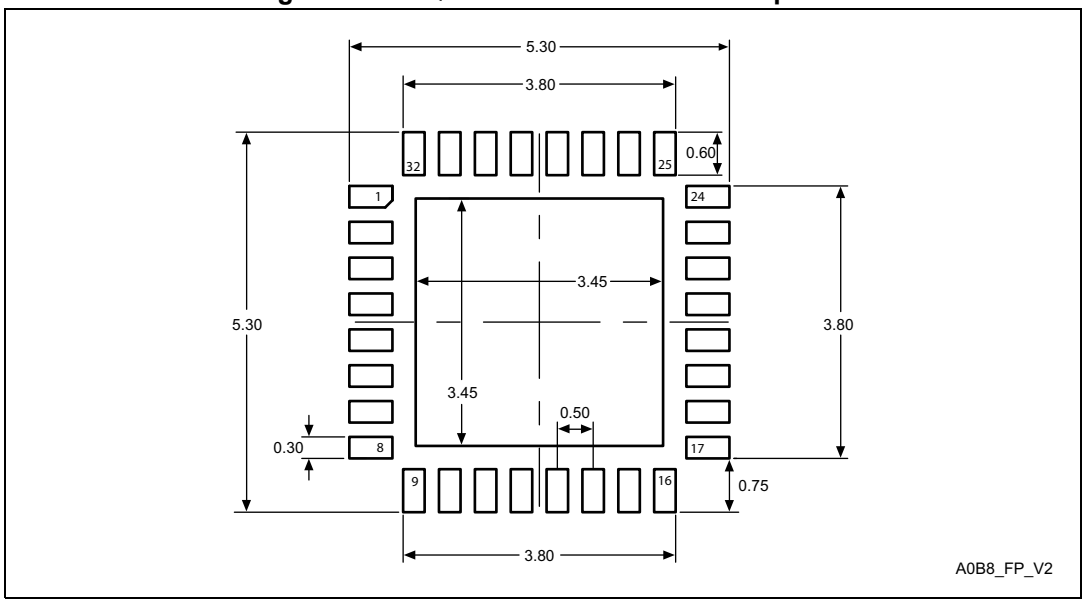
7.2 LQFP32 package information

Figure 37. LQFP32, 7 x 7 mm, 32-pin low-profile quad flat package outline



1. Drawing is not to scale.

Figure 41. UFQFPN32 recommended footprint

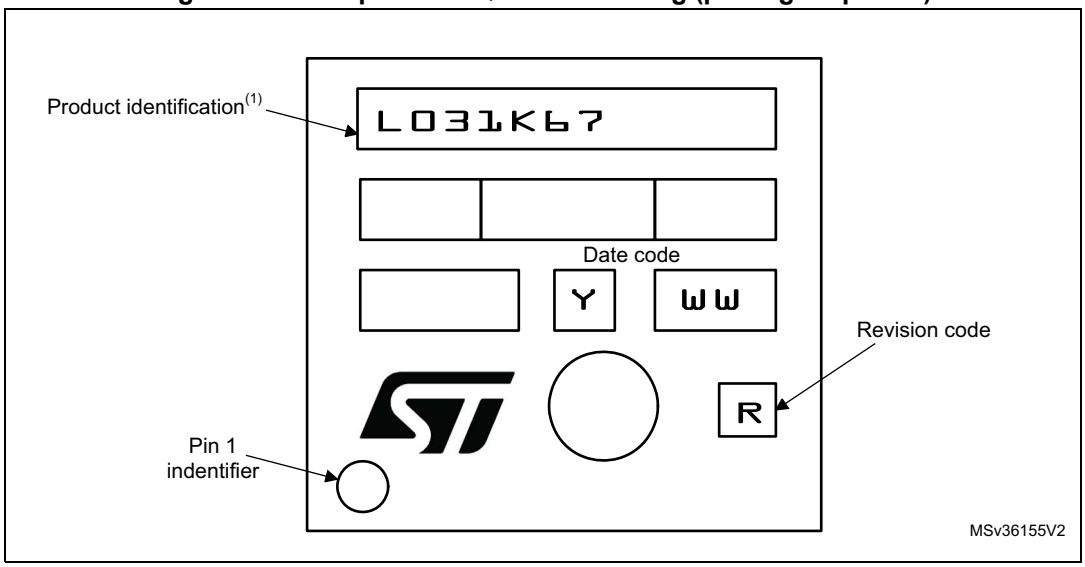


1. Dimensions are expressed in millimeters.

UFQFPN32 device marking

The following figure gives an example of topside marking versus pin 1 position identifier location.

Figure 42. Example of UFQFPN32 marking (package top view)



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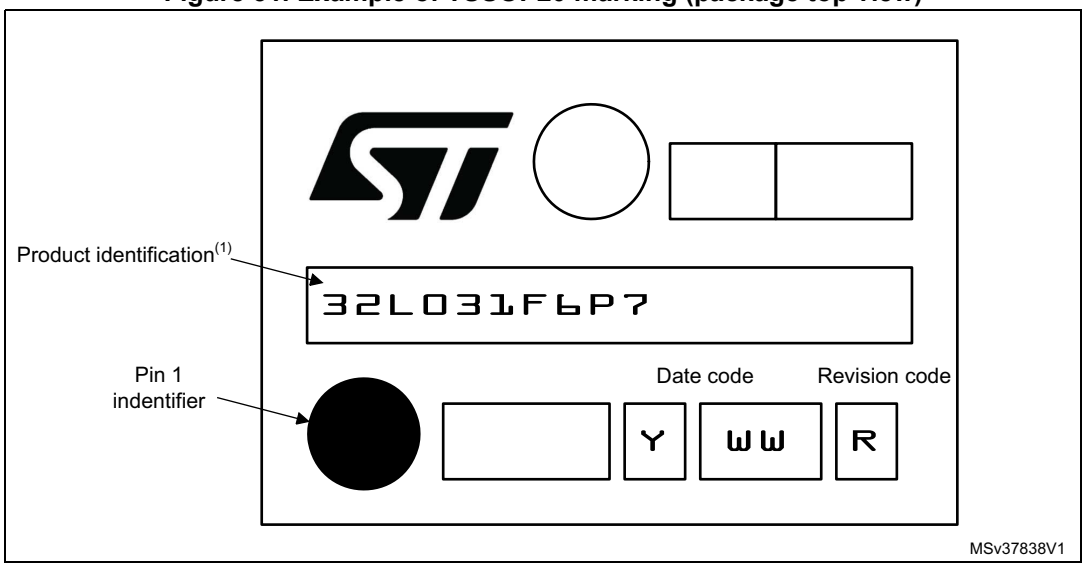
TSSOP20 device marking

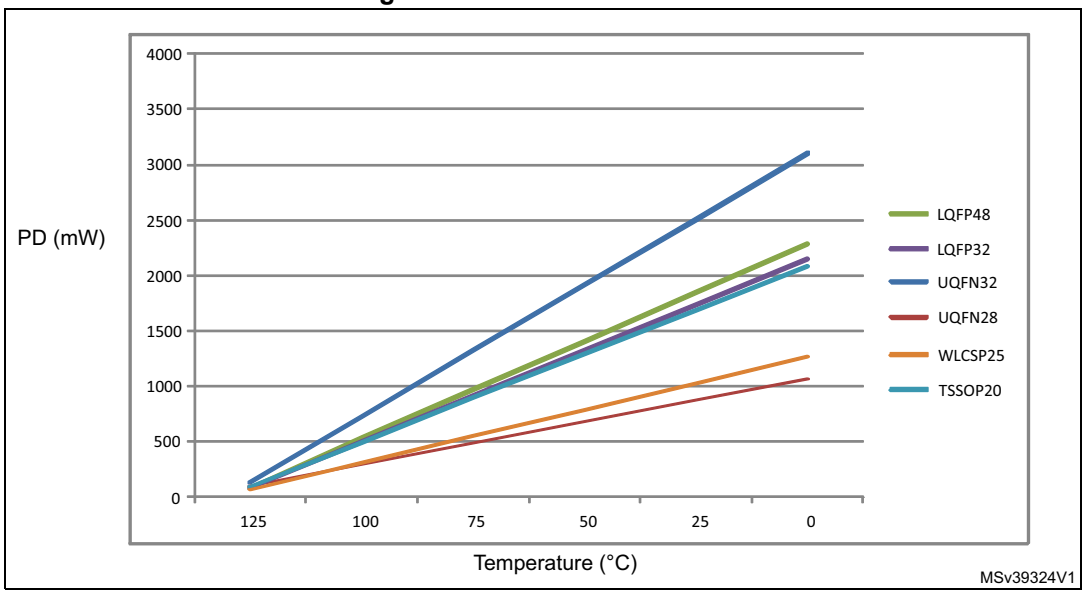
The following figure gives an example of topside marking versus pin 1 position identifier location.

Figure 51. Example of TSSOP20 marking (package top view)



1. Parts marked as “ES”, “E” or accompanied by an Engineering Sample notification letter, are not yet qualified and therefore not yet ready to be used in production and any consequences deriving from such usage will not be at ST charge. In no event, ST will be liable for any customer usage of these engineering samples in production. ST Quality has to be contacted prior to any decision to use these Engineering samples to run qualification activity.

Figure 52. Thermal resistance



1. The above curves are valid for range 6. For range 7, the curves are shifted by 20 °C to the right.

7.7.1 Reference document

JESD51-2 Integrated Circuits Thermal Test Method Environment Conditions - Natural Convection (Still Air). Available from www.jedec.org.

9 Revision history

Table 79. Document revision history

Date	Revision	Changes
18-Sep-2015	1	Initial release.
22-Oct-2015	2	Datasheet status changed to production data.Updated power consumption in run mode on cover page. Updated *Table 5: Functionalities depending on the working mode (from Run/active down to standby)*. Modified *Figure 6: STM32L031x4/6 UFQFPN28 pinout* and *Table 15: Pin definitions*. Updated power dissipation (P_D) in *Table 20: General operating conditions*. Updated current consumption with all peripherals enabled in *Table 34: Peripheral current consumption in Run or Sleep mode* and *Table 35: Peripheral current consumption in Stop and Standby mode*. Modified t_{WSTOP} for f_{HCLK}=65 MHz in *Table 36: Low-power mode wakeup timings*. Updated *Table 24: Current consumption in Run mode, code with data processing running from Flash memory*, *Table 25: Current consumption in Run mode vs code type, code with data processing running from Flash memory*, *Figure 15: IDD vs VDD, at TA= 25/55/85/105 °C, Run mode, code running from Flash memory, Range 2, HSE = 16 MHz, 1WS* and *Figure 16: IDD vs VDD, at TA= 25/55/85/105 °C, Run mode, code running from Flash memory, Range 2, HSI16, 1WS*. Updated*Table 26: Current consumption in Run mode, code with data processing running from RAM* and *Table 27: Current consumption in Run mode vs code type, code with data processing running from RAM*, *Table 28: Current consumption in Sleep mode*. Updated *Table 29: Current consumption in Low-power run mode* and *Figure 17: IDD vs VDD, at TA= 25/55/ 85/105/125 °C, Low-power run mode, code running from RAM, Range 3, MSI (Range 0) at 64 KHz, 0 WS*. Updated *Table 30: Current consumption in Low-power Sleep mode*. Updated *Table 31: Typical and maximum current consumptions in Stop mode*, *Table 32: Typical and maximum current consumptions in Standby mode*, *Figure 18: IDD vs VDD, at TA= 25/55/ 85/105/125 °C, Stop mode with RTC enabled and running on LSE Low drive* and *Figure 19: IDD vs VDD, at TA= 25/55/85/105/125 °C, Stop mode with RTC disabled, all clocks off*. Updated *Table 48: EMS characteristics* and *Table 49: EMI characteristics*.